



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#12/Amend B
Amend
9/17/02

In re application of

Docket No: Q61572

Noriaki ODA

Appln. No.: 09/739,620

Group Art Unit: 2812

Confirmation No.: 4739

Examiner: Ha Nguyen

Filed: December 20, 2000

For: SEMICONDUCTOR DEVICE WITH COPPER-BASED WIRING LINES AND
METHOD OF FABRICATING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated March 7, 2002, please amend the above-identified
application as follows:

IN THE CLAIMS:

Please cancel claims 3, 6 and 12-24 without prejudice or disclaimer.

Please enter the following amended claims:

1. (Twice Amended) A semiconductor device comprising:

- (a) a substrate having a surface;
- (b) a dielectric formed over the surface of the substrate; and
- (c) a wiring line buried in the dielectric;

the wiring line including a Cu-based conductor and a first cover layer covering an outer
surface of the conductor;

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